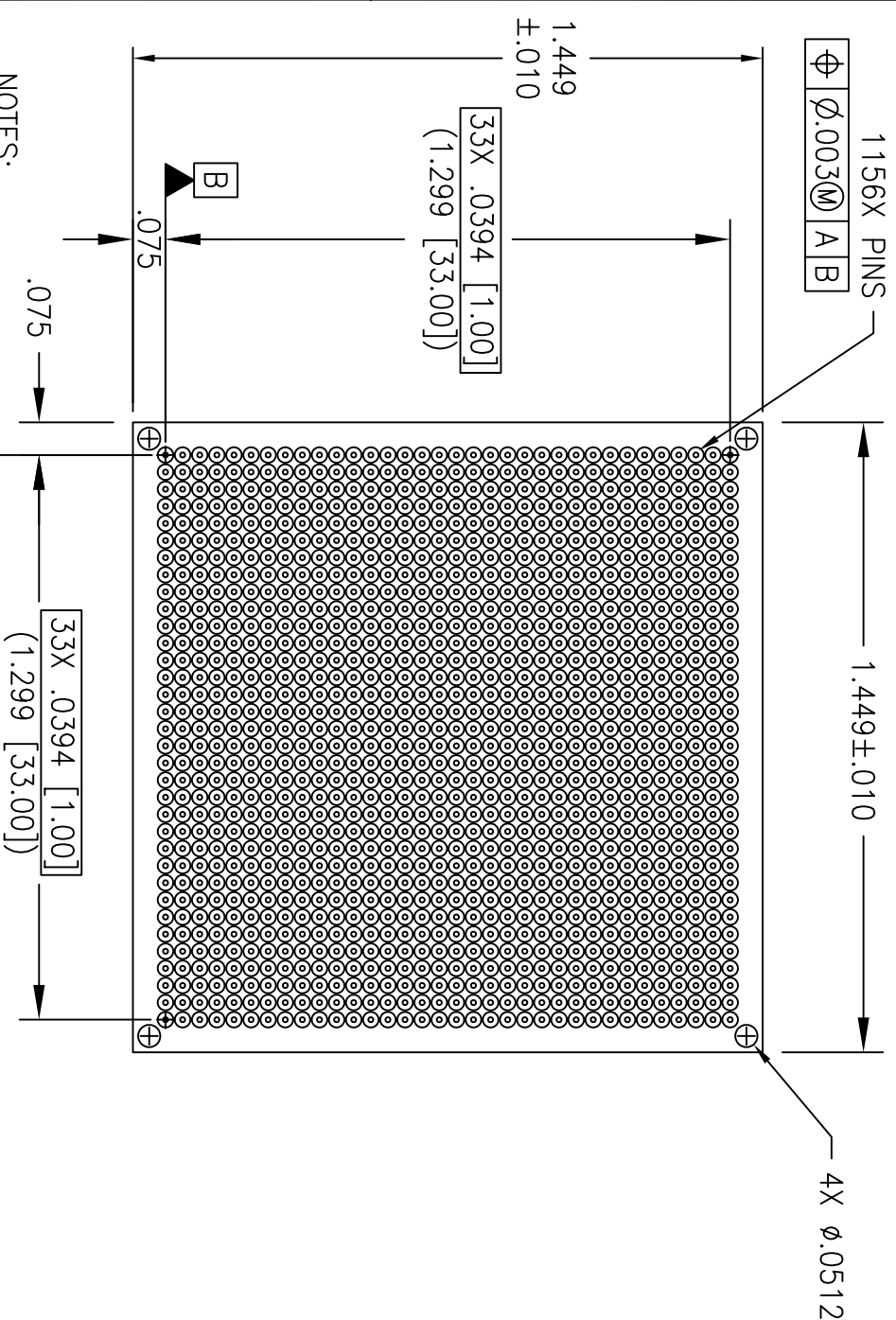


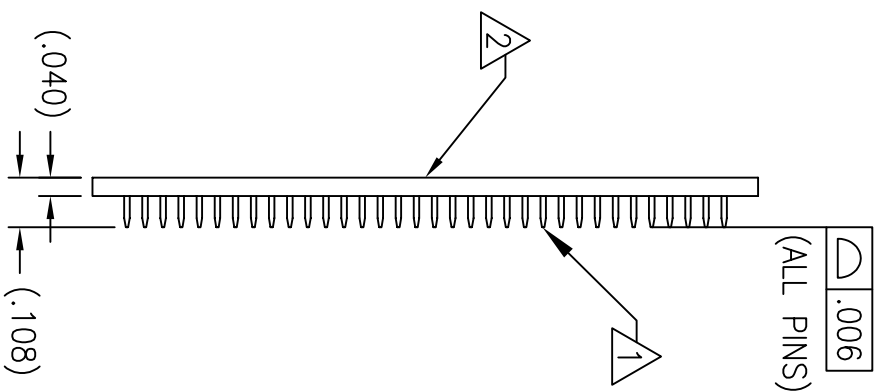
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REV	DESCRIPTION	EGN	DATE	RELEASE
1	SALES RELEASE			

TOP VIEW



RS VIEW



- NOTES:
- PINS Φ .0117
 MATERIAL: PHOSPHOR BRONZE.
 PLATING: HARD GOLD OVER NICKEL.
 - INSULATOR MATERIAL: FR4.

UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN INCHES TOLERANCES: ANGLES: ± 1/64 FRACTIONS: ± 1/64 DECIMALS: .XXX ±.005 .XXXX ±.0005		CONTRACT NO.	DESIGNER	DATE	DATE	DATE	DATE	DATE	DATE	DATE	DATE	DATE
DRAWN BY		DESIGNER	DATE	DATE	DATE	DATE	DATE	DATE	DATE	DATE	DATE	
CHECKER		DATE	DATE	DATE	DATE	DATE	DATE	DATE	DATE	DATE	DATE	
PROCESS ENG.		DATE	DATE	DATE	DATE	DATE	DATE	DATE	DATE	DATE	DATE	
TITLE		SCALE	DRAWING NO.	REV	REV	REV	REV	REV	REV	REV	REV	
HIL0-BGA PIN BASE 34 X 34, 1156 PINS 1mm PITCH		N/A	HLP-341156-B-10	1	1	1	1	1	1	1	1	
INTERCONNECT SYSTEMS INC. 708 VIA ALONDRA, CAMARILLO, CA 93012		FINISHED ASST: HLP-341156-B-10	SHEET 1 OF 1									